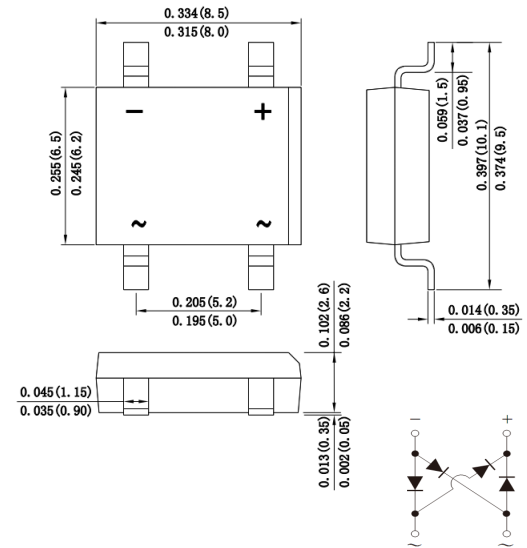


DBS
Features

The plastic package carries Underwriters Laboratory
Flammability Classification 94V-0
Idea for printed circuit board
Glass passivated junction chip
Low reverse leakage
High forward surge current capability
High temperature soldering guaranteed
260 C/10 seconds at terminals

Mechanical Data

Case : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0078 ounce, 0.22 grams



Dimensions in inches and (millimeters)

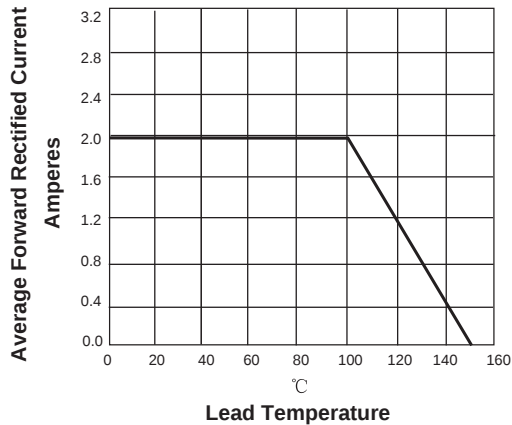
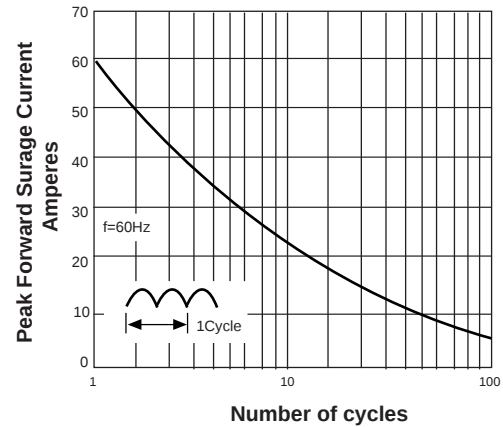
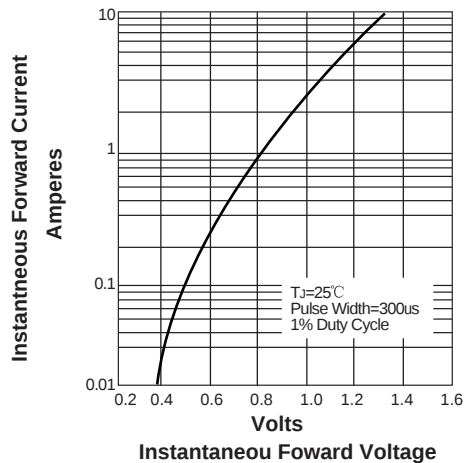
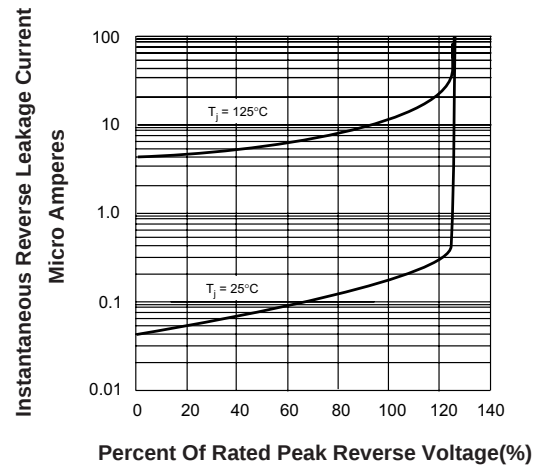
Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

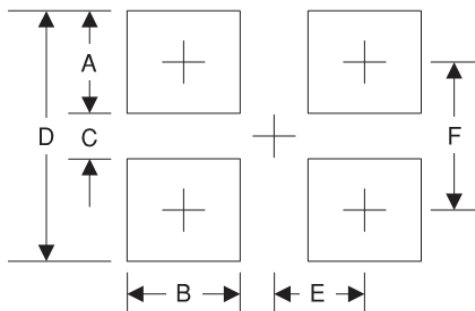
Parameter	SYMBOLS	DB207S	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC blocking voltage	V_{DC}	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	2.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	60.0	A
Rating for fusing ($t=8.3\text{ms}$, $T_a=25^\circ\text{C}$)	I_t^2	14.9	A^2s
Maximum instantaneous forward voltage at 2.0A	V_F	1.0	V
Maximum DC reverse current $T_A = 25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	2.0 200	μA
Typical junction capacitance (Note 1)	C_J	25.0	pF
Typical thermal resistance	R_{QA}	67.0	$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

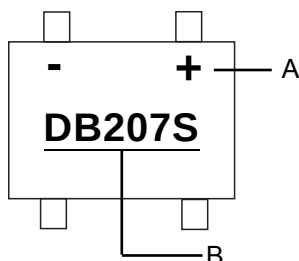
FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS


Suggested Pad Layout



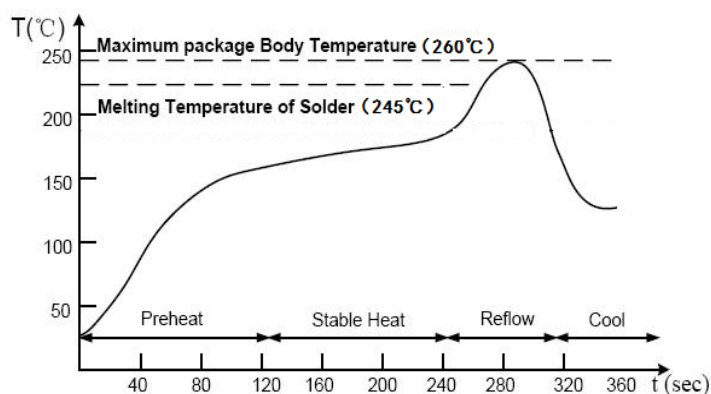
Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
B	1.3	0.051
C	6.90	0.272
D	11.5	0.453
E	2.6	0.102
F	9.20	0.362

Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name

Suggested Soldering Temperature Profile



Note

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.

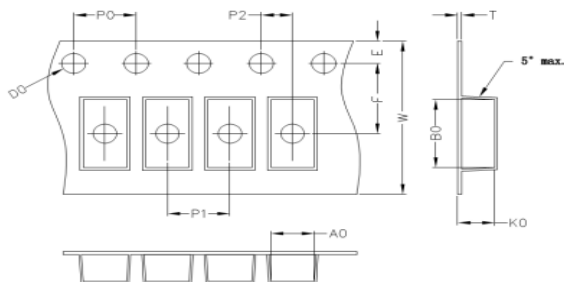
The device can be exposed to a maximum temperature of 260°C for 10 seconds.

Devices can be cleaned using standard industry methods and solvents.

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
8.64	10.4	3.3	1.55	1.75	7.50
P0	P1	P2	T	W	Tolerance
4.0	12.0	2.0	0.30	16	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
DBS	13'	330	1.5	338	3	365*365*360	20

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